Thick Film Chip Resistors / Low Resistance Type

ERJ R, B: 0402, 0603, 0805, 1206, 1210, 1812, 2512 ERJ L: 0603, 0805, 1206, 1210, 1812, 2010, 2512

Type: ERJ 2B, 3R, 3B, 6R, 6B, 8R, 8B,

14R, 14B, 12R, 1TR

ERJ L03, L06, L08, L14, L12,

L1D, L1W



R10

R10

R10

R10

Features

Small size and lightweight
For PCB size reduction and lightweight products

High reliability

Metal glaze thick film resistive element and three layers of electrodes result in high reliability

Solderability

Suitable for both reflow soldering and flow soldering

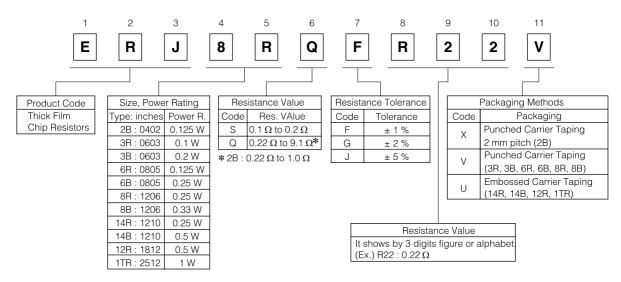
Low Resistance Value
2B Type: 0.1 Ω to 1.0 Ω

3R, 3B, 6R, 6B, 8R, 8B, 14R, 14B, 12R, 1TR Type : 0.1 Ω to 9.1 Ω

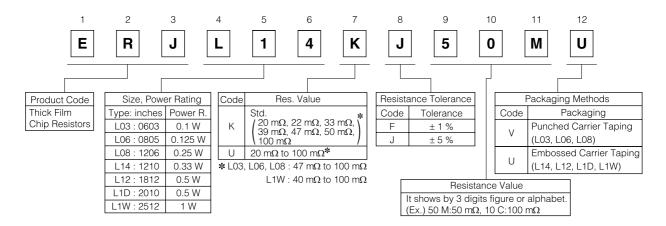
L03, L06, L08 Type : 47 m Ω to 100 m Ω L14, L12 Type : 20 m Ω to 100 m Ω L1D, L1W Type : 40 m Ω to 100 m Ω

 Reference Standards IEC 60115-8, JIS C 5201-8

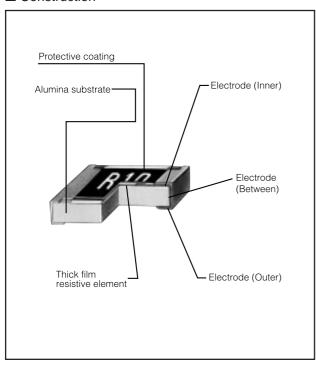
■ Explanation of Part Numbers (2B, 3R, 3B, 6R, 6B, 8R, 8B, 14R, 14B, 12R, 1TR Type)



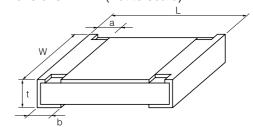
■ Explanation of Part Numbers (L03, L06, L08, L14, L12, L1D, L1W Type)



■ Construction



■ Dimensions in mm (not to scale)



	Тур	ne e		Dime	ensions (mm)		Mass(Weight)
	(inch		L	W	а	b	t	[g/1000 pcs.]
NEW	ERJ2B	(0402)	1.00 ^{±0.10}	$0.50^{+0.10}_{-0.05}$	0.20±0.10	0.27 ^{±0.10}	0.35 ^{±0.05}	0.8
	ERJ3R							
	ERJ3B	(0603)	1.60 ^{±0.15}	$0.80\substack{+0.15 \\ -0.05}$	0.30 ^{±0.20}	$0.30^{\pm0.15}$	0.45 ^{±0.10}	2
	ERJL03							
	ERJ6R							
	ERJ6B	(0805)	2.00 ^{±0.20}	1.25 ^{±0.10}	0.40 ^{±0.20}	$0.40^{\pm0.20}$	0.60 ^{±0.10}	4
	ERJL06							
	ERJ8R		-0.20	-0.15				
	ERJ8B	(1206)	3.20+0.05	1.60+0.05	0.50 ^{±0.20}	$0.50^{\pm0.20}$	0.60 ^{±0.10}	10
	ERJL08							
	ERJ14R							
	ERJ14B	(1210)	3.20 ^{±0.20}	$2.50^{\pm0.20}$	0.50 ^{±0.20}	$0.50^{\pm0.20}$	0.60 ^{±0.10}	16
	ERJL14							
	ERJ12R	(1812)	4.50±0.20	3.20±0.20	0.50±0.20	0.50±0.20	0.60±0.10	27
	ERJL12	(1012)			0.50	0.50	0.00	21
	ERJL1D	(2010)	5.00 ^{±0.20}	2.50±0.20		$0.60^{\pm0.20}$		27
	ERJ1TR	(2512)		3.20 ^{±0.20}				45
	ERJL1W	(2512)	6.40 ^{±0.20}	$3.20^{\pm0.20}$	$0.65^{\pm0.20}$	1.30 ^{±0.20}	1.10 ^{±0.10}	79

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Ratings

<Low resistance type>

Type (inches)	Power Rating at 70 °C (W)	Resistance Tolerance (%)	Resistance Range (Ω)	T.C.R. [×10 ⁻⁶ /°C (ppm/°C)]	Category Temperature Range (Operating Temperature Range) (°C)
ERJL03 (0603)	0.1 (0.2) * ¹	±1, ±5	47 m to 100 m *2	±200	-55 to +125
ERJL06 (0805)	0.125 (0.25) *1	±1, ±5	47 m to 100 m *2	±100	-55 to +125
ERJL08 (1206)	0.25 (0.33) *1	±1, ±5	47 m to 100 m *2	±100	-55 to +125
ERJL14 (1210)	0.33	±1, ±5	20 m to 100 m *2		-55 to +125
ERJL12 (1812)	0.5	±1, ±5	20 m to 100 m *2	R<47 mΩ:±300	-55 to +125
ERJL1D (2010)	0.5	±1, ±5	40 m to 100 m *2	R≧47 mΩ:±100	-55 to +125
ERJL1W (2512)	1	±1, ±5	40 m to 100 m *2		-55 to +125

^{*1} Please ask us when resistors guaranteed high power are needed.

<High power type>

Type (inches)		Power Rating at 70 °C (W)	Resistance Tolerance (%)	Resistance Range (Ω)	T.C.R. [×10 ⁻⁶ /°C (ppm/°C)]	Category Temperature Range (Operating Temperature Range) (°C)	
ERJ2BS	(0402)	0.105	±2, ±5	0.10 to 0.20 (E24)	±300	55	
ERJ2BQ	(0402)	0.125	±1, ±2, ±5	0.22 to 1.0 (E24)	±250	-55 to +125	
ERJ3BS	(0603)			0.10 to 0.20 (E24)	. 200		
ED IODO	(0000)	0.2	±1, ±2, ±5	0.22 to 0.91 (E24)	±300	-55 to +125	
ERJ3BQ	(0603)			1.0 to 9.1 (E24)	±200]	
ERJ6BS	(0805)			0.10 to 0.20 (E24)	050		
ED ICDO	(0005)	0.25	±1, ±2, ±5	0.22 to 0.91 (E24)	±250	-55 to +125	
ERJ6BQ (0805)			1.0 to 9.1 (E24)	±200	1		
ERJ8BS	(1206)			0.10 to 0.20 (E24)	. 050		
ED 1000	(4000)	0.33	±1, ±2, ±5	0.22 to 0.91 (E24)	±250	-55 to +125	
ERJ8BQ	(1206)			1.0 to 9.1 (E24)	±200	1	
ERJ14BS	(1210)			0.10 to 0.20 (E24)	. 000		
ED 14 4DO	(4040)	0.50	±1, ±2, ±5	0.22 to 0.91 (E24)	±200	-55 to +125	
ERJ14BQ (1210)				1.0 to 9.1 (E24)	±100		

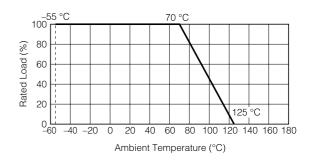
<Standard type>

Type (inches)		Power Rating at 70 °C (W)	Resistance Tolerance (%)	Resistance Range (Ω)		T.C.R. [×10 ⁻⁶ /°C (ppm/°C)]	Category Temperature Range (Operating Temperature Range) (°C)
ERJ3RS	(0603)			0.10 to 0.20	(E24)	±300	
ERJ3RQ	(0603)	0.1	±1, ±2, ±5	0.22 to 0.91	(E24)		-55 to +125
	,			1.0 to 9.1	(E24)	±200	
ERJ6RS	(0805)			0.10 to 0.20	(E24)	±250	
ERJ6RQ	(0805)	0.125	±1, ±2, ±5	0.22 to 0.91	(E24)	1230	-55 to +125
ENJONG	(0005)			1.0 to 9.1	(E24)	±200	
ERJ8RS	(1206)			0.10 to 0.20	(E24)	. 250	
ED IODO	(4000)	0.25	±1, ±2, ±5	0.22 to 0.91	(E24)	±250	-55 to +125
ERJ8RQ	(1206)			1.0 to 9.1	(E24)	±200	
ERJ14RS	(1210)			0.10 to 0.20	(E24)	. 200	
ED 144DO	(4040)	0.25	±1, ±2, ±5	0.22 to 0.91	(E24)	±200	-55 to +125
ERJ14RQ	(1210)			1.0 to 9.1	(E24)	±100	
ERJ12RS	(1812)			0.10 to 0.20	(E24)	. 200	
ED MODO	(4040)	0.5	±1, ±2, ±5	0.22 to 0.91	(E24)	±200	-55 to +125
ERJ12RQ	(1812)			1.0 to 9.1	(E24)	±100	
ERJ1TRS	(2512)			0.10 to 0.20	(E24)	. 000	
ED MEDO	(0540)	1	±1, ±2, ±5	0.22 to 0.91	(E24)	±200	-55 to +125
ERJ1TRQ	(2512)			1.0 to 9.1	(E24)	±100	

^{*2} Standard R.V. : 20 m Ω , 22 m Ω , 33 m Ω , 39 m Ω , 47 m Ω , 50 m Ω , 100 m Ω , Custom R.V. : Each 1 m Ω within upper range.

Power Derating Curve

For resistors operated in ambient temperatures above 70 $^{\circ}$ C, power rating shall be derated in accordance with the right figure.

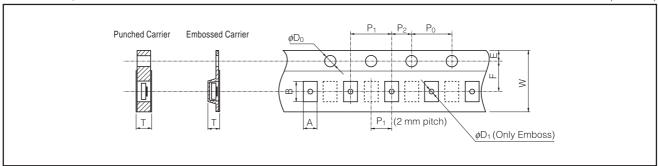


■ Packaging Methods (Taping)

Standard Quantity

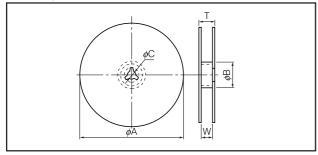
Туре	Kind of Taping	Pitch (P ₁)	Quantity		
ERJ2B		2 mm	10000 pcs./reel		
ERJ3R, 3B, L03	Punched Carrier Taping				
ERJ6R, 6B, L06	Tunenca Carrier raping				
ERJ8R, 8B, L08			5000 pag /rool		
ERJ14R, 14B, L14		4 mm	5000 pcs./reel		
ERJ12R, L12		4 111111			
ERJL1D	Embossed Carrier Taping				
ERJ1TR			4000 pcs./reel		
ERJL1W			3000 pcs./reel		

● Carrier Tape (Unit:mm)



Туре	А	В	W	F	Е	P ₁	P ₂	P ₀	ϕD_0	Т	ϕD_1
ERJ2B	0.70 ^{±0.05}	1.20 ^{±0.05}				2.00 ^{±0.10}				0.52 ^{±0.05}	-
ERJ3R,3B,L03	1.10 ^{±0.10}	1.90 ^{±0.10}	8.00±0.20							0.70 ^{±0.05}	-
ERJ6R,6B,L06	1.65 ^{±0.15}	2.50±0.20	0.00	3.50 ^{±0.05}	1.75 ^{±0.10}		2.00±0.05	4.00 ^{±0.10}	1.50+0.10	0.84 ^{±0.05}	-
ERJ8R,8B,L08	2.00±0.15	3.60 ^{±0.20}									-
ERJ14R,14B,L14	2.80±0.20	3.50 ^{±0.20}	8.00 ^{±0.30}			4.00 ^{±0.10} 2.					1.0+0.10
ERJ12R,L12	3.50±0.20	4.80 ^{±0.20}				4.00				1.00±0.10	
ERJL1D	2.80±0.20	5.30 ^{±0.20}	12.00±0.30	5.50±0.20						1.00	1.5 min.
ERJ1TR	3.60±0.20	6.90 ^{±0.20}	12.00=	3.30====							1.5 11111.
ERJL1W	3.60±0.20	6.90 ^{±0.20}								1.60 ^{±0.10}	

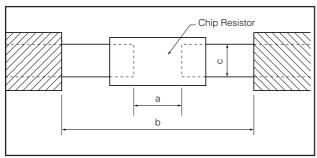
Taping Reel



					(Unit : mm)
Type	φΑ	ϕ B	φC	W	Т
ERJ2B					
ERJ3R,3B,L03					
ERJ6R,6B,L06				9.0 ^{±1.0}	11.4 ^{±1.0}
ERJ8R,8B,L08					
ERJ14R,14B,L14	180.0+0	60 min.	13.0±1.0		
ERJ12R,L12					
ERJL1D				13.0±1.0	15.4 ^{±2.0}
ERJ1TR				13.0=	13.4===
ERJL1W					

■ Recommended Land Pattern

In the case of flow soldering, the land width must be smaller than the Chip Resistor width to control the solder amount properly. Generally, the land width should be 0.7 to 0.8 times (W) of the width of chip resistor. In the case of reflow soldering, solder amount can be adjusted, therefor the land width should be set to 1.0 to 1.3 times chip resistor width (W).

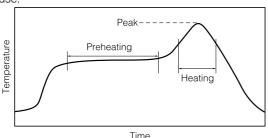


Type (inches)		Dimensions (mm)				
1) 00 (11101	100)	а	b	С		
ERJ2B	(0402)	0.5 to 0.6	1.4 to 1.6	0.4 to 0.6		
ERJ3R, 3B, L03	(0603)	0.7 to 0.9	2 to 2.2	0.8 to 1		
ERJ6R, 6B, L06	(0805)	1 to 1.4	3.2 to 3.8	0.9 to 1.4		
ERJ8R, 8B, L08	(1206)	2 to 2.4	4.4 to 5	1.2 to 1.8		
ERJ14R, 14B, L14	(1210)	2 to 2.4	4.4 to 5	1.8 to 2.8		
ERJ12R, L12	(1812)	3.3 to 3.7	5.7 to 6.5	2.3 to 3.5		
ERJL1D	(2010)	3.6 to 4	6.2 to 7	1.8 to 2.8		
ERJ1TR	(2512)	5 to 5.4	7.6 to 8.6	2.3 to 3.5		
ERJL1W	(2512)	3.6 to 4	7.6 to 8.6	2.3 to 3.5		

■ Recommended Soldering Conditions

Recommendations and precautions are described below.

- Recommended soldering conditions for reflow
- ·Reflow soldering shall be two times maximum.
- Please contact us for additional information when you use in conditions other than those specified.
- Please measure a temperature of terminations and study solderability every kind of solder and board, before actual use.



For solder (Example : Sn/Pb)

	Temperature	Time		
Preheating	140 °C to 160 °C	60 s to 120 s		
Main heating	Above 200 °C	30 s to 40 s		
Peak	235 ± 5 °C	max. 10 s		

For lead-free solder (Example : Sn/Ag/Cu)

	Temperature	Time
Preheating	150 °C to 180 °C	60 s to 120 s
Main heating	Above 230 °C	30 s to 40 s
Peak	max. 260 °C	max. 10 s

Recommended soldering conditions for flow

	For	solder	For lead-free solder		
	Temperature	Time	Temperature	Time	
Preheating	140 °C to 160 °C	60 s to 120 s	150 °C to 180 °C	60 s to 120 s	
Soldering	245±5 °C	20 s to 30 s	max. 260 °C	max. 10 s	

The following are precautions for individual products. Please also refer to the precautions common to Fixed Resistors shown on page ER3 of this catalog.

- 1. Take measures against mechanical stress during and after mounting of Thick Film Chip Resistors (hereafter called the Resistors) so as not to damage their electrodes and protective coatings.
- 2. If a transient load (heavy load in a short time) like a pulse is expected to be applied, check and evaluate the operations of the Resistors when installed in your products before use.
 - Never exceed the rated power. Otherwise, the performance and/or reliability of the Resistors may be impaired.
- 3. Do not use halogen-based or other high-activity flux. Otherwise, the residue may impair the Resistors' performance and/or reliability.
- 4. When soldering with a soldering iron, never touch the Resistors' bodies with the tip of the soldering iron. When using a soldering iron with a high temperature tip, finish the soldering as quickly as possible (within three seconds at 350 °C max.).
- 5. As the amount of applied solder becomes larger, the mechanical stress applied to the Resistors increases, causing problems such as cracks and faulty characteristics. Avoid applying an excessive amount of solder.
- 6. Do not apply a shock to the Resistors or pinch them with a hard tool (e.g. pliers and tweezers). Otherwise, the Resistors' protective coatings and bodies may be chipped, affecting their performance.
- 7. Avoid excessive bend of printed circuit boards in order to protect the Resistors from abnormal stress.

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(Common precautions for Fixed Resistors)

- When using our products, no matter what sort of equipment they might be used for, be sure to make a written agreement on the specifications with us in advance. The design and specifications in this catalog are subject to change without prior notice.
- Do not use the products beyond the specifications described in this catalog.
- This catalog explains the quality and performance of the products as individual components. Before use, check and evaluate their operations when installed in your products.
- Install the following systems for a failsafe design to ensure safety if these products are to be used in equipment where a defect in these products may cause the loss of human life or other significant damage, such as damage to vehicles (automobile, train, vessel), traffic lights, medical equipment, aerospace equipment, electric heating appliances, combustion/gas equipment, rotating equipment, and disaster/crime prevention equipment.
- * Systems equipped with a protection circuit and a protection device
- * Systems equipped with a redundant circuit or other system to prevent an unsafe status in the event of a single fault

(1) Precautions for use

- These products are designed and manufactured for general purpose and standard use in general electronic equip ment (e.g. AV equipment, home electric appliances, office equipment, information and communication equipment)
- These products are not intended for use in the following special conditions. Before using the products, carefully check the effects on their quality and performance, and determine whether or not they can be used.
 - 1. In liquid, such as water, oil, chemicals, or organic solvent
 - 2. In direct sunlight, outdoors, or in dust
 - 3. In salty air or air with a high concentration of corrosive gas, such as Cl2, H2S, NH3, SO2, or NO2
 - 4. In an environment where strong static electricity or electromagnetic waves exist
 - 5. In an environment where these products cause dew condensation
 - 6. Sealing or coating of these products or a printed circuit board on which these products are mounted, with resin or other materials
- These products generate Joule heat when energized. Carefully position these products so that their heat will not affect the other components.
- Carefully position these products so that their temperatures will not exceed the category temperature range due to the effects of neighboring heat-generating components. Do not mount or place heat-generating components or inflammables, such as vinyl-coated wires, near these products.
- Note that non-cleaning solder, halogen-based highly active flux, or water-soluble flux may deteriorate the perfor mance or reliability of the products.
- Carefully select a flux cleaning agent for use after soldering. An unsuitable agent may deteriorate the performance or reliability. In particular, when using water or a water-soluble cleaning agent, be careful not to leave water residues. Otherwise, the insulation performance may be deteriorated.

(2) Precautions for storage

The performance of these products, including the solderability, is guaranteed for a year from the date of arrival at your company, provided that they remain packed as they were when delivered and stored at a temperature of $5\,^{\circ}$ C to $35\,^{\circ}$ C and a relative humidity of $45\,^{\circ}$ K to $85\,^{\circ}$ K.

Even within the above guarantee periods, do not store these products in the following conditions. Otherwise, their electrical performance and/or solderability may be deteriorated, and the packaging materials (e.g. taping materials) may be deformed or deteriorated, resulting in mounting failures.

- 1. In salty air or in air with a high concentration of corrosive gas, such as Cl₂, H₂S, NH₃, SO₂, or NO₂
- 2. In direct sunlight

<Package markings>

Package markings include the product number, quantity, and country of origin. In principle, the country of origin should be indicated in English.